

Electronic Patent Application Fee Transmittal

Application Number:	10552441
Filing Date:	07-Oct-2005
Title of Invention:	Epoxy resin molding material for sealing use and semiconductor device
First Named Inventor/Applicant Name:	Ryoichi Ikezawa
Filer:	William Ivan Solomon/Stacey Keaton
Attorney Docket Number:	1204.45467X00

Filed as Large Entity

U.S. National Stage under 35 USC 371 Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				
Extension - 1 month with \$0 paid	1251	1	120	120

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				120